

MONT-BLANC

🌐 montblanc-project.eu | @MontBlanc_EU

Paving the way to a scalable, modular and power-efficient European HPC processor

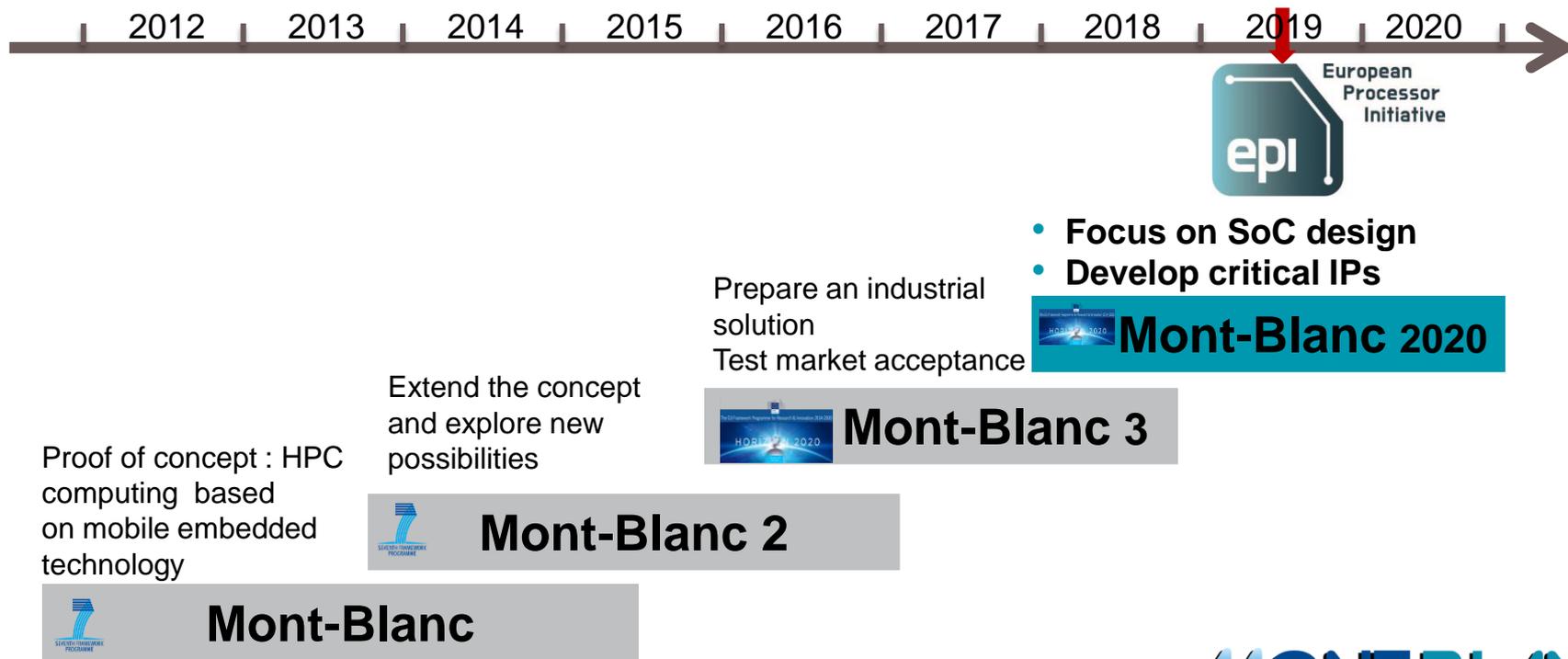
Arm HPC User's Group @ISC'19

Said Derradji (Atos)



Mont-Blanc roadmap

Vision: leverage the fast growing market of mobile technology for scientific computation



Mont-Blanc 2020 partners

Atos arm



- **Trigger the development of the next generation of industrial processor for Big Data and High Performance Computing**

- **Mont-Blanc DNA**
 - economic sustainability
 - power efficiency
 - heterogeneity
 - strong codesign approach for real applications
 - building a prototype

Mont-Blanc prototypes

2015

2016

2017

2018

2019

2020

Mont-Blanc prototype



1080 Dual Cortex-A15 (+ Mali)

❖ 2160 Armv7 cores

Dibona



48 nodes bi-socket THX2

❖ 3072 Armv8 cores

MB2020 Demonstrator



Only one MB2020 SoC

❖ 32 SVE cores

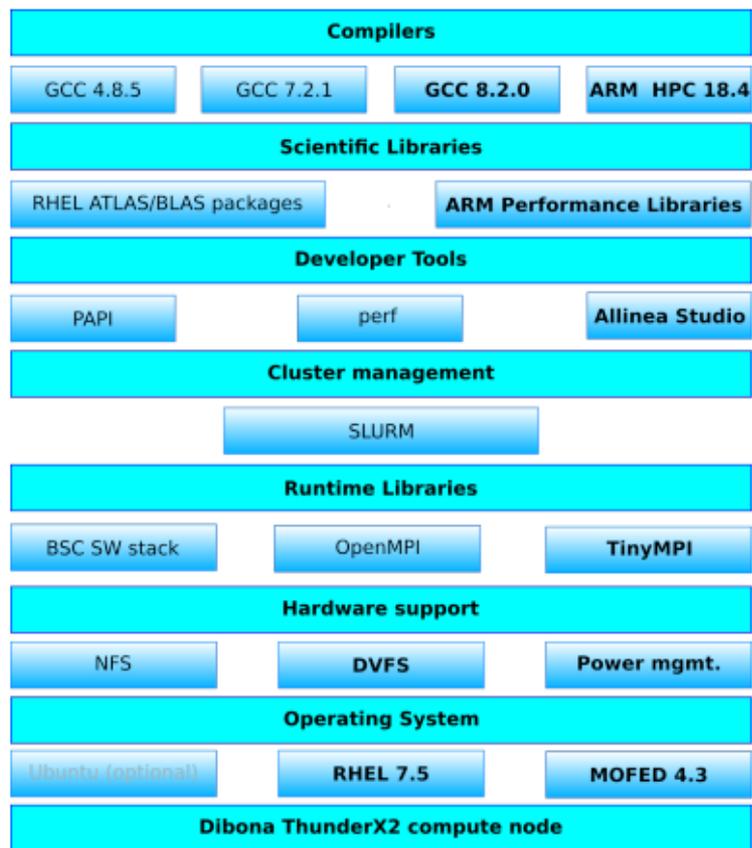
Mont-Blanc Dibona open to more users

- **The Mont-Blanc Dibona prototype:**
 - 48 nodes bi-socket THX2 @2GHz (3072 cores)
 - 12.3 TB RAM
 - featuring Mellanox EDR 100Gb/s
 - Theoretical peak performance of > 49 Tflops
- **Usage:**
 - +70 users
 - Allocations with SLURM (including bash): 15k
 - Application executions with SLURM: 12.5k
 - Multi-node jobs with SLURM: ~5.7k
- **Events:**
 - Hackathon by Arm @SC18 +40 users
 - Hackathon by BSC Feb. 21st +30 students



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Dibona SW stack today



- ▶ Atos ARM Lab still updating the SW stack providing more OpenMPI flavors
- ▶ ARM provides new Compiler, Performance Libraries
- ▶ HW support :Atos fine grain power monitoring, DVFS
- ▶ RedHat: More recent and optimized kernel
- ▶ Mellanox: Improved drivers
- ▶ Preparing the porting/developing of Atos BXI drivers on Arm

Introducing BullSequana XH2000



Atos is the industrial pivot of Mont-Blanc project
ARM is one of the Bull strategic directions for the next years
Europe is sponsoring ARM development

using best in class CPU/GPU/FPGA



using standard and proprietary interconnects

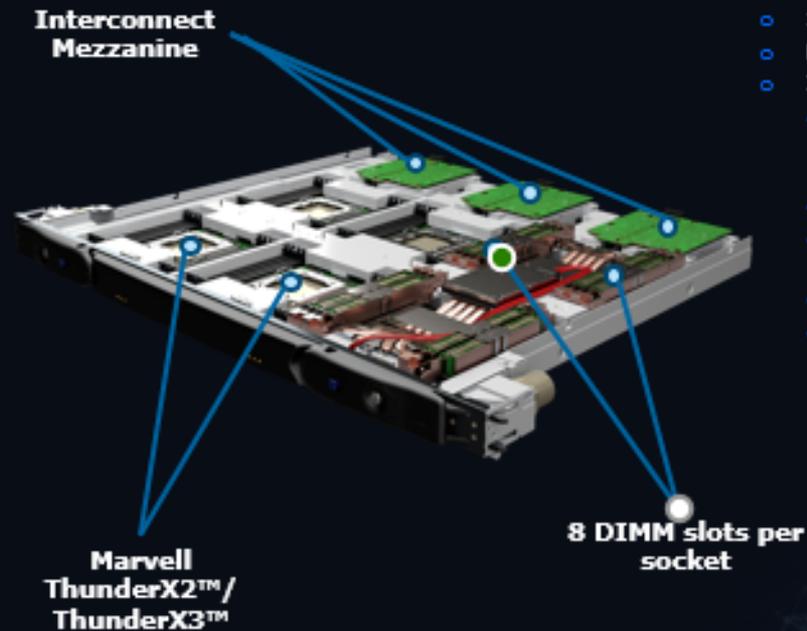


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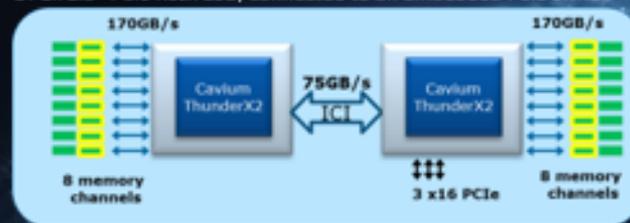


BullSequana XH2000 Blades

BullSequana X1310: Marvell ThunderX2™/ThunderX3™ (ARMv8) processor



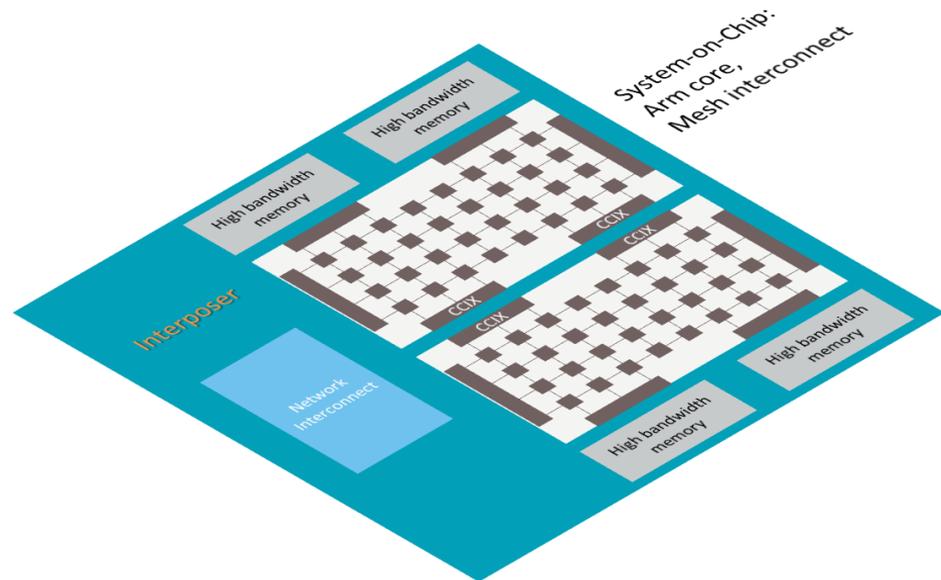
- o 1U form factor
- o Direct liquid cooling
- o 3 compute nodes per blade with:
 - o 2 Marvell ThunderX2/ThunderX3 processors with
 - o Up to 32 custom ARMv8 cores per CPU, 4 threads per core, up to 2.5GHz
 - o 16 DDR4 @2666MT/s DIMM slots
 - o 1 Interconnect mezzanine board (High-speed Ethernet, InfiniBand EDR, HDR or HDR100)
 - o 1 optional PCIe switch mezzanine
 - o Disks
 - o 1 x 2.5" 7 mm SATA SSD
 - o Or 1x 2.5" PCIe flash SSD, connected to an embedded PCIe switch



Project Objectives

Mont-Blanc 2020 will provide new IPs, such as a new low-power “Network-on-Chip” based on the Coherent Hub Interface (CHI) architecture:

- supporting up to 128 SVE cores;
- each core embedding 2 vector units from 128 to 1024 bits wide;
- interfacing HBM2/3 memory controllers to sustain high memory bandwidth.



3 Key Challenges

To achieve the desired performance with the targeted power consumption, the project will need to:



understand the trade-offs between vector length, NoC bandwidth and memory bandwidth to maximize processing unit efficiency;



come up with an innovative on-die interconnect that can deliver enough bandwidth with minimum energy consumption;



opt for a high-bandwidth / low power memory solution with enough capacity and bandwidth for Exascale applications.

MB2020 main choices

- **To use the ARM ISA**

- **To design, implement and leverage new technologies to improve the performance, power efficiency, reliability and security of the processor :**
 - large SVE compute units
 - specific NoC
 - specific High Bandwidth Memory controller
 - specific SoC Power Management controller
 - innovative packaging technologies (Interposer)
 - state of the art silicon process 7nm FF

- **To improve on the economic sustainability of processor development through a modular design that allows to retarget our SoC for different markets adding specific accelerators.**

From design to HW emulation

- **Objectives:** verification of MB2020 design (interconnection network and memory hierarchy) and performance extractions
- **Methodology:** emulation of the MB2020 design with applicative workflow based on simulation traces injected into the design
 - Trace injector are playing the role of ARM cores in the design

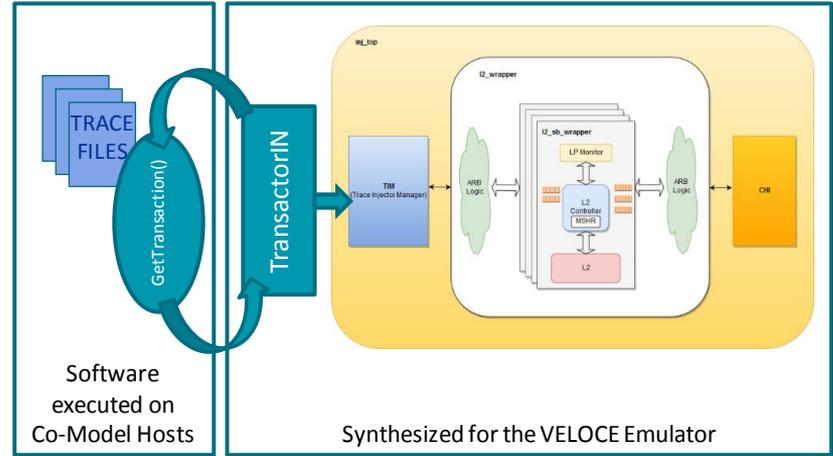


Mentor Graphics Veloce2: Powerful emulator environment hosted by CEA

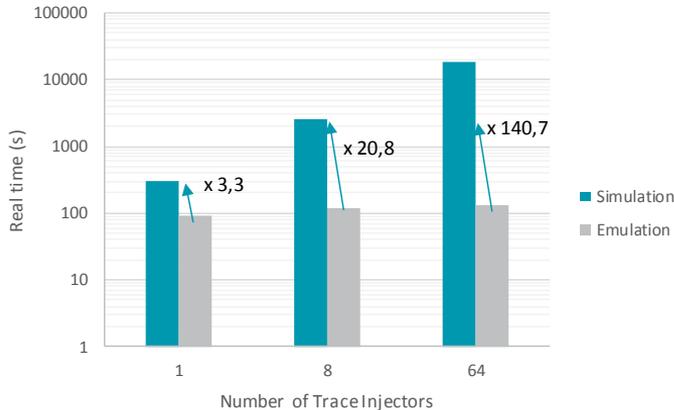
- Up to 2MHz emulation speed
- 200 Mbytes max capacity
- 32 Gb memory capacity

HW emulator accelerated simulation

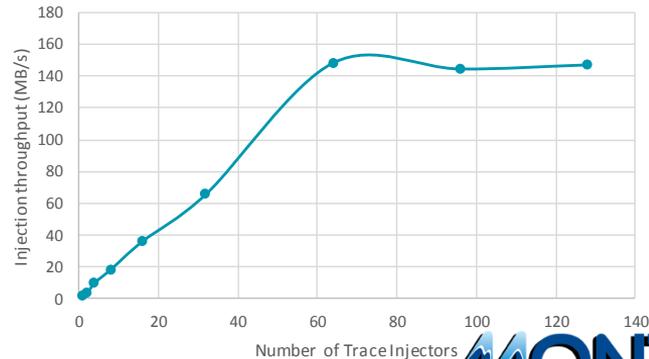
- **Validation of the trace injector design on the emulator**
 - HW/SW interface for trace file injection in the emulator
 - RTL code fully synthesizable for the HW part
 - Configurable number of Trace Injectors
- **Measurement of emulation performance compared to simulation**
- **Measurement of aggregated injection throughput during the emulation**
- **Emulation environment ready to integrate the MB2020 design**



RTL simulation time compared to emulation time for the same design

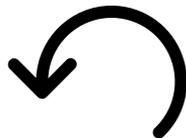


Aggregated injection throughput during the emulation



Codesign from Apps to architecture

setting NoC parameters
evaluate performance using traces
identify HW bottleneck
then try new parameters or new features

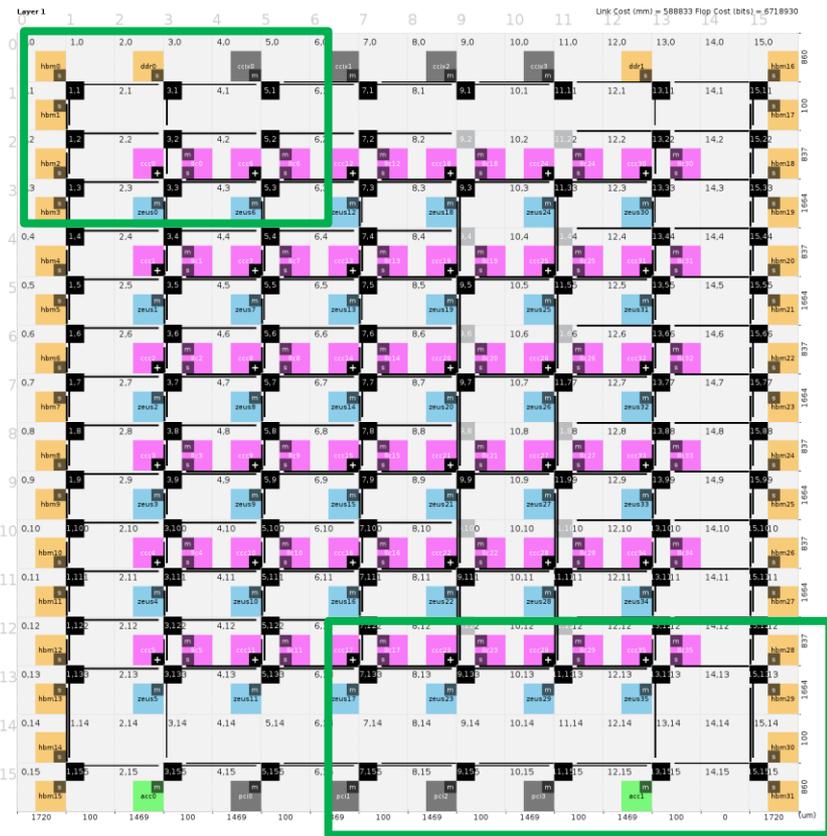


Message class/BW: the CHI coherence protocol is mapped over several physical layers:

- Data, Response, Request, Snoop
- Each message class can be mapped to several lanes to sustain the BW required per channel

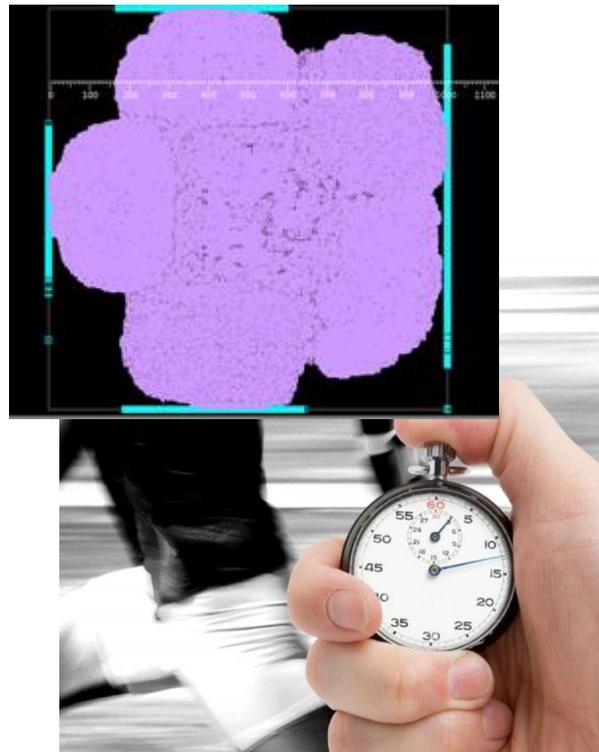
Memory mapping/affinity :

- the home agent/snoop filter must be distributed
- the interleaving function (per group per cache line) must assure well-balanced traffic spreading to memory (home agents and controllers).



Demonstrating the performance

- Power, Performance and Area (PPA) metrics in 7nm
- Using IP RTL, back-end design team will run topographical synthesis (=taking physical info into account) using Design Compiler NXT from Synopsys
- Providing estimations for all IPs, including SVE cores



Beyond Mont-Blanc 2020

- **Mont-Blanc 2020 is at the heart of the European exascale supercomputer effort**
- **Most of the IP developed within Mont-Blanc 2020 will be reused and productized in the European Processor Initiative (EPI)**



MONT-BLANC 2020

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